

ABSTRACT

BARRIER CHEMICAL MECHANICAL PLANARIZATION SLURRIES

USING CERIA-COATED SILICA ABRASIVES

Chemical Mechanical Planarization (CMP) polishing compositions comprising composite particles, such as ceria coated silica particles, offer tunable polishing removal selectivity values between different films. Compositions enable high removal rates on interconnect metal and the silicon oxide dielectric while providing a polish stop on low-K dielectrics, a-
5 Si and tungsten films. Chemical Mechanical Planarization (CMP) polishing compositions have shown excellent performance using soft polishing pad.

(No drawing to accompany the abstract)